PDPM

Indian Institute of Information Technology, Design & Manufacturing, Jabalpur

(An Institute of National Importance established by an act of Parliament, under MHRD, Govt. of India)

Dumna Airport Road, PO: Khamaria, Jabalpur-482005(MP) INDIA

ROLLING ADVERTISEMENT FOR FACULTY POSITIONS

Dated: 02/02/2016

Advertisement No. 2/2016

PDPM Indian Institute of Information Technology, Design and Manufacturing, Jabalpur, an Institute of national importance, established by an act of Parliament under Ministry of Human Resource Development, Government of India invites applications from well qualified and strongly motivated candidates for faculty positions at the level of Assistant Professor (on contract in AGPs of Rs. 6000/- and Rs. 7000/-) in the disciplines of Computer Science and Engineering (CSE), Electronics & Communication Engineering (ECE), Mechanical Engineering (ME), Design, Natural Sciences (Physics, Mathematics and English). Areas of specialisation in the required disciplines are as below:-

1. Data Structures and Algorithms 2. Parallel and Distributed Computing 3. Mobile and Internet Technology 4. Data Engineering 5. Cycper and System Intelligence 6. Machine Learning and Artificial Intelligence 7. Image Processing and Computer Vision 8. Software and System Engineering 9. Network and Communication 2. ECE Discipline 1. Micro and Nano Electronics 2. Advanced Signal Processing 3. Power and Control 4. Microwave and Communication 5. Sensor and Actuator 6. Microprocessors and Microcontrollers 7. Robotics 8. Automation 9. Embedded System 3. ME Discipline 1. Manufacturing Processes 2. Vibration, Tribology and Condition Monitoring 3. Smart Materials and Composites 4. Heat Transfer and Hydraulic Machines 5. CFD/FEM 6. Gas Turbine Design 7. Fracture and Fatigue 8. Industrial Engineering and Management 9. CAD/CAM/CIM 4. Design Discipline 1. Product Design 2. Industrial Design 3. Visual/Communication Design 4. Interaction Design 5. Design Management	Sl No	Name of Discipline	Area of Specialization				
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5. Design Management			4. Interaction Design				
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5	Natural Sciences					
(I)	(Physics)	1. Quantum/Nuclear Physics				
		2. Laser/Quantum Optics/Spectroscopy				
		3. Condensed Matter Theory & experimental/Applied Physics/Nano Science				
(II)	(Mathematics)	1. Analysis				
		2. Optimization				
		3. Number Theory				
		4. Probability and Statistics				
		5. Computation PDEs				
		6. Spectral Methods/Finite Elements Methods				
(III)	(English)	1. English Language Teaching				
		2. English Literature				
		3. Communication and Personality Development & Soft Skill				

01. Detail of Educational qualification and experience required for the posts.

Designation, Pay Band and Academic Grade Pay	Essential Qualification	Relevant Experience	Other essential requirements	Additional Desirable requireme nts
Assistant Professor (on contract), PB-3 with Grade Pay of Rs. 6000/-+ 07 additional non-compounded increments	Ph.D.	None	None	One publication in an SCI Journal
Assistant Professor (on contract), PB-3 with Grade Pay of Rs. 7000/-	Ph.D.	01 year	One paper accepted for publication in SCI Journal	Two papers in SCI Journals or one patent; may be based on Ph.D. work.

NOTE: - Reservation for SC/ST/OBC/PWD candidates will be as applicable.

2. Instructions to the applicants:-

- 1. Application forms may be downloaded from the Institute's website: www.iiitdmj.ac.in.
- 2. Applications received up to March 15, 2016 (5:00 pm) would be processed together in first phase. However, Institute will decide the cut-off date for applications received thereafter and process the applications from time to time as per the requirements.
- 3. Separate application must be filled up if a candidate is applying for a faculty position in more than one discipline or for more than one post.
- 4. Full and comprehensive details of teaching experience/research experience /industrial experience should be given while applying with the evidences from the competent authority. Only relevant document issued by competent authority should be attached while filling the form.
- 5. Attach separate sheet in the same format, if required.
- 6. Incomplete/ partially filled application forms will not be considered. Applications not in prescribed format or without self-attested copies of certificates/ mark sheets, proof of date of birth, etc. (mentioned in check list), application without signature or any extra sheet not signed may be rejected. Decision of the Institute authorities in such cases will be final.
- 7. Persons employed in Government/Semi- Government Organization or Educational Institution must apply through proper channel. However, a copy of duly filled application may be sent as an "Advance Copy" so as to reach this office before the due date of submission.
- 8. No correspondence will be entertained from candidates regarding postal delays, conduct & result of interview, reasons for not being called for interview.
- 9. The Institute reserves the right to fill or not to fill any or all the posts advertised.
- 10. Canvassing in any form will be a disqualification.
- 11. Applications sent through email/FAX will not be considered.
- 12. Incomplete applications / without necessary enclosures will summarily be rejected.
- 13. Envelope containing application form should be super-scribed with "APPLICATION FOR THE POST OF ASSISTANT PROFESSOR (ON CONTRACT) IN CSE/ME/ECE/DESIGN/NATURAL SCIENCES (PHYSICS/MATHEMATICS/ENGLISH)".
- 14. Complete application form in hard copy along with all the enclosures/annexure must be forwarded at the address given below.
- 15. Applicants are also required to forward only scanned copy of their application form (without any enclosures/annexure) on the email-id -facapp@iiitdmj.ac.in also.
- 16. Applications forwarded only as scanned copy on the email not followed by hard copy, will not be considered.
- 17. Applications which are not strictly as per the format given will be summarily rejected. Bio-data/Curriculum vitae etc. will also not be considered and will be summarily rejected.
- 18. Applicants should go through the advertisement thoroughly and should fill up all the required information in the prescribed proforma as asked for.

- 19. Candidates called for interview will be reimbursed AC-3 train fare (only for travel within India) by the shortest route/bus fare as per Govt. of India norms. Candidates from overseas are also encouraged to apply. The Institute holds web interviews for such candidates. No correspondence will be entertained from candidates regarding postal delays conduct and result of interviews and reasons for not being called for interview.
- 20. Applicants are requested to look at website of PDPM-IIITDMJ (www.iiitdmj.ac.in) from time to time for information, updates etc.
- 21. Address for correspondence: Assistant Registrar (Establishment), PDPM IIITDM Jabalpur, Dumna Airport Road, PO Khamaria, Jabalpur. 482005 (MP) (India)

3. Facilities available to the faculties

- 1. Reimbursement of relocation charges up to Rs. 90,000/-for faculty from abroad for reimbursement of air fare for self and spouse and cost of transportation of goods is admissible as per Institute /Govt. of India norms. Reimbursement for self and family and transport of goods for faculty joining from within India is also applicable as per rules of the Institute/ Govt. of India.
- 2. The Institute provides a Cumulative Professional Development Allowance (CPDA) of Rs. 3 lakhs for every block of three years as per MHRD Govt. of India orders.
- 3. The posts carry allowances such as HRA TA, DA-at present 119% Reimbursement of Children Education Allowance (up to 2 children) Medical facilities, facility of LTC as per GOI/Institute Rules.
- 4. The Institute encourages interaction of the faculty with industry and other research and professional institution.

4. Note:-

- The posts are on purely contract basis for a fixed period of time. After completion of the said period, contract will
 cease and employee will be relieved of his duties. Institute in no condition will be bound to continue employing the
 employee beyond the contract period.
- 2) Candidates should have an excellent academic record, good communication skills, a commitment to high quality undergraduate and post-graduate education and research.
- 3) Mere meeting the minimum education qualification and experience does not qualify an applicant for call for an interview and selection etc. Short listing criteria for calling for interview may be fixed higher than those in the advertisement.
- 4) A candidate applying for a post can be called for interview for lower post also, if Committee recommends so.
- 5) A candidate may be offered lower Post/AGP/Scale of Pay other than the post for which the applicant would be called for interview based on his performance, qualification and experience etc before the selection Committee.

DIRECTOR